



N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
001/	60mΩ @ V _{GS} = 8V	3.9A
30V	$72m\Omega$ @ V _{GS} = 4.5V	3.5A

Description

This new generation MOSFET is designed to minimize the footprint in handheld and mobile application. The device can be used to replace many small signal MOSFETs with minimal footprint.

Applications

- Battery Management
- Load Switch
- Battery Protection
- Handheld and Mobile Application

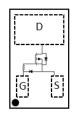
Features and Benefits

- Low Qg & Qgd
- Small Footprint
- Low Profile 0.20mm Height
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please <u>contact us</u> or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

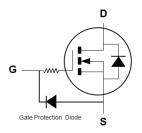
Mechanical Data

- Case: X4-DSN1006-3
- Terminal Connections: See Diagram Below
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu or NiAu. Solderable per MIL-STD-202, Method 208 (e4)
- Weight: 0.00029 grams (Approximate)

X4-DSN1006-3



Top View



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN3060LCA3-7	X4-DSN1006-3	10000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

Marking Information



 $\begin{array}{l} P = Product\ Type\ Marking\ Code \\ YM = Date\ Code\ Marking \\ Y\ or\ \overline{Y} = Year\ (ex:\ I=2021) \\ M\ or\ \overline{M} = Month\ (ex:\ 9=September) \end{array}$

Date Code Key

Year	2017		2021	2022	2023	2024	2025	2026	2027	2028	2029	2030
Code	E			J	K	L	М	N	0	Р	R	S
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code										-	Ν	_



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	V _{DSS}	30	V		
Gate-Source Voltage	Vgss	12	V		
Continuous Drain Current (Note 5) Vgs = 8V	Steady State	T _A = +25°C T _A = +70°C	lo	3.9 3.1	А
Continuous Drain Current (Note 5) V _{GS} = 4.5V	ID	3.5 2.8	А		
Pulsed Drain Current (Note 6)	I _{DM}	20	А		

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 7)	PD	0.79	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 7)	Reja	160	°C/W
Power Dissipation (Note 5)	PD	1.35	W
Thermal Resistance, Junction to Ambient @T _A = +25°C (Note 5)	Reja	93	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

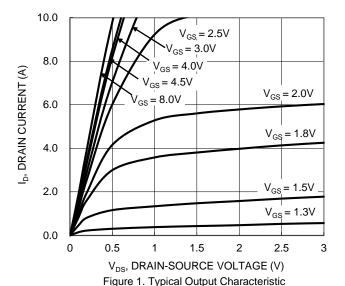
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)			•	•	•		
Drain-Source Breakdown Voltage	BVDSS	30	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	IDSS		_	100	nA	V _{DS} = 24V, V _{GS} = 0V	
Gate-Source Leakage	Igss	_	_	50	nA	Vgs = 10V, Vps = 0V	
ON CHARACTERISTICS (Note 8)						•	
Gate Threshold Voltage	VGS(TH)	0.65	0.83	1.10	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
		l	46	60		$V_{GS} = 8V, I_{D} = 0.5A$	
Static Drain-Source On-Resistance	Dagger		52	72	mΩ	$V_{GS} = 4.5V, I_{D} = 0.5A$	
Static Drain-Source On-Nesistance	RDS(ON)	_	69	110	11122	$V_{GS} = 2.5V, I_{D} = 0.5A$	
		_	101	160		$V_{GS} = 1.8V, I_{D} = 0.5A$	
Diode Forward Voltage	VsD	_	0.7	0.9	V	$V_{GS} = 0V, I_{S} = 0.5A$	
Reverse Recovery Charge	Qrr	_	2.4	_	nC	V _{DD} = 15V, I _F = 0.5A,	
Reverse Recovery Time	t _{RR}	_	7.1	_	ns	di/dt = 300A/µs	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	Ciss	_	128	_		15)/)/ 0)/	
Output Capacitance	Coss	_	81	_	pF	$V_{DS} = 15V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	Crss	_	6.3	_		I - I.OIVII IZ	
Series Gate Resistance	Rg	_	20.9	_	Ω	f = 1MHz, V _{GS} = 0V, V _{DS} = 0V	
Total Gate Charge	Qg		1118	_			
Gate-Source Charge	Qgs	_	163	_		$V_{GS} = 4.5V, V_{DS} = 15V,$	
Gate-Drain Charge	Qgd	_	241	_	рС	$I_D = 0.5A$	
Gate Charge at VTH	Q _{g(TH)}		130	_			
Turn-On Delay Time	t _{D(ON)}		5.3	_			
Turn-On Rise Time	tR	1	2.1	_		$V_{DS} = 15V, V_{GS} = 4.5V,$	
Turn-Off Delay Time	tD(OFF)		12.9	_	ns	$R_g = 2\Omega$, $I_D = 0.5A$	
Turn-Off Fall Time	tF	_	5.4	_			

Notes:

- Device mounted on FR-4 material with 1-inch² (6.45-cm²), 2-oz. (0.071-mm thick) Cu.
 Repetitive rating, pulse width limited by junction temperature.
 Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
 Short duration pulse test used to minimize self-heating effect.
 Guaranteed by design. Not subject to production testing.





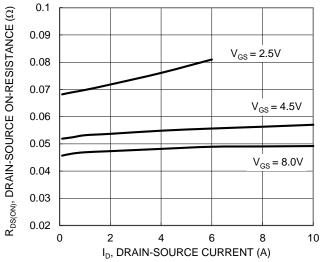


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

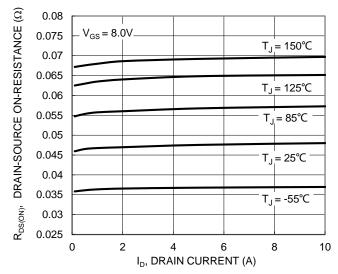


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

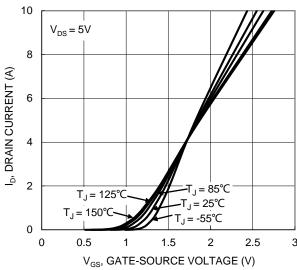


Figure 2. Typical Transfer Characteristic

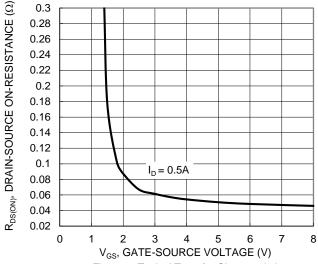


Figure 4. Typical Transfer Characteristic

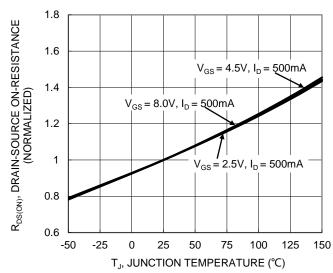


Figure 6. On-Resistance Variation with Junction Temperature



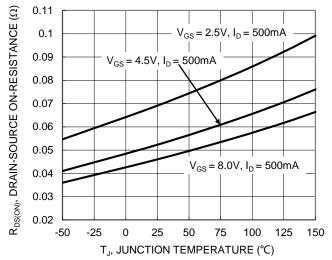


Figure 7. On-Resistance Variation with Junction Temperature

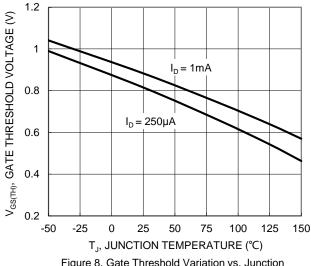


Figure 8. Gate Threshold Variation vs. Junction Temperature

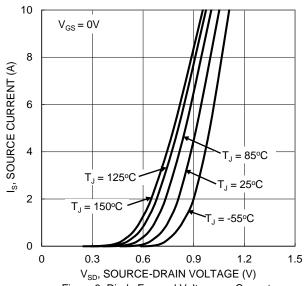
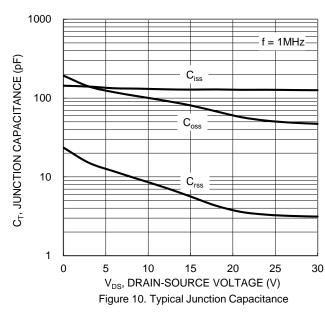


Figure 9. Diode Forward Voltage vs. Current



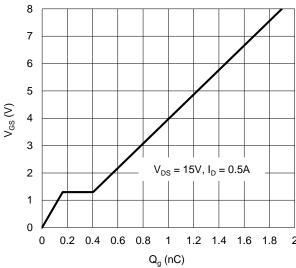
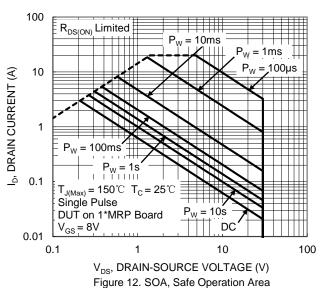


Figure 11. Gate Charge





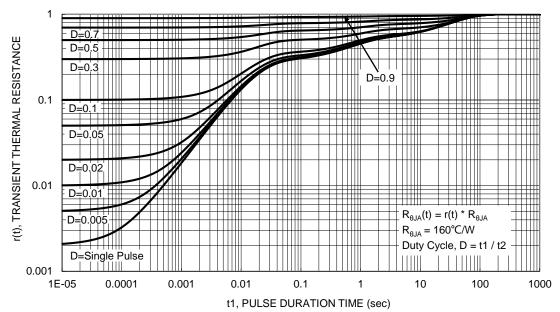


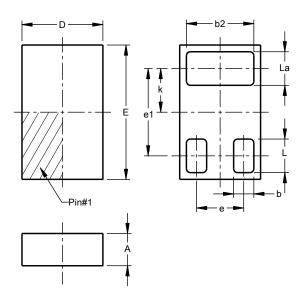
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

X4-DSN1006-3

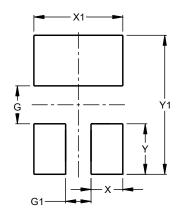


X4-DSN1006-3						
Dim	Min Max Typ					
Α	0.18	0.22	0.20			
b	0.14	0.16	0.15			
b2	0.49	0.51	0.50			
D	0.56	0.64	0.60			
E	0.96	1.04	1.00			
е	_	_	0.35			
e1	_	_	0.65			
k	_	_	0.325			
L	0.24	0.26	0.25			
La	0.24	0.26	0.25			
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X4-DSN1006-3



Dimensions	Value (in mm)				
G	0.40				
G1	0.20				
X	0.15				
X1	0.50				
Y	0.25				
Y1	0.90				



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